

Product Summary

| BV _{DSS} | R _{DSON} Max | I _D Max T _A = +25°C |
|-------------------|--------------------------------|--|
| 40V | 11.5mΩ @ V _{GS} = 10V | 11.6A |
| | 18mΩ @ V _{GS} = 4.5V | 9.3A |

Description

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

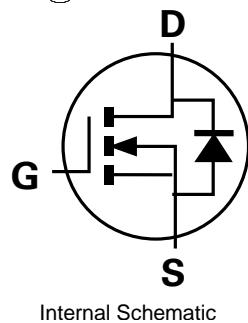
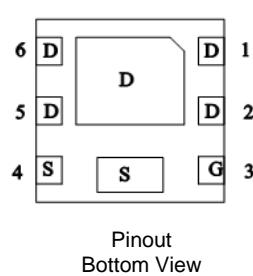
- Power-management functions
- DC-DC converters
- Backlighting

Features

- Rated to +175°C – Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching, Test in Production – Ensures More Reliable and Robust End Application
- Low $R_{DS(ON)}$ – Ensures On-State Losses Are Minimized
- 0.6mm Profile – Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. “Green” Device (Note 3)
- This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.
<https://www.diodes.com/quality/product-definitions/>
- An automotive-compliant part is available under a separate datasheet (**DMTH4008LFDFWQ**)

Mechanical Data

- Package: U-DFN2020-6
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 **(e3)**
- Weight: 0.007 grams (Approximate)



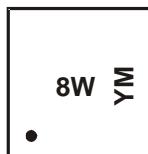
Ordering Information (Note 4)

| Orderable Part Number | Package | Packing | |
|-----------------------|--------------------------|---------|---------|
| | | Qty. | Carrier |
| DMTH4008LFDFW-7 | U-DFN2020-6/SWP (Type F) | 3,000 | Reel |
| DMTH4008LFDFW-13 | U-DFN2020-6/SWP (Type F) | 10,000 | Reel |

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



8W = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: M = 2025)
M = Month (ex: 9 = September)

Date Code Key

| | | | | | | | | | | | | |
|-------|------|-----|------|------|------|------|------|------|------|------|------|------|
| Year | 2018 | - | 2025 | 2026 | 2027 | 2028 | 2029 | 2030 | 2031 | 2032 | 2033 | 2034 |
| Code | F | - | M | N | P | R | S | T | U | V | W | X |
| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | O | N | D |

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | |
|---|---|----------|-------------|---|
| Drain-Source Voltage | V_{DSS} | 40 | V | |
| Gate-Source Voltage | V_{GSS} | ± 20 | V | |
| Continuous Drain Current (Note 7) $V_{GS} = 10\text{V}$ | $T_A = +25^\circ\text{C}$ $T_A = +100^\circ\text{C}$ | I_D | 11.6 8.2 | A |
| Pulsed Drain Current (10 μs Pulse, Duty Cycle = 1%) | I_{DM} | 80 | A | |
| Continuous Source-Drain Diode Current (Note 7) | I_S | 2.55 | A | |
| Pulsed Source-Drain Diode Current (10 μs Pulse, Duty Cycle = 1%) | I_{SM} | 80 | A | |
| Avalanche Current, $L = 0.3\text{mH}$ (Note 8) | I_{AS} | 14.7 | A | |
| Avalanche Energy, $L = 0.3\text{mH}$ (Note 8) | E_{AS} | 32.4 | mJ | |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit | |
|--|---------------------------|-----------------|------------------|---------------------------|
| Total Power Dissipation (Note 5) | $T_A = +25^\circ\text{C}$ | P_D | 0.99 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady State | $R_{\theta JA}$ | 153 | $^\circ\text{C}/\text{W}$ |
| Total Power Dissipation (Note 6) | $T_A = +25^\circ\text{C}$ | P_D | 2.35 | W |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady State | $R_{\theta JA}$ | 64.5 | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance, Junction to Case (Note 7) | $T_C = +25^\circ\text{C}$ | $R_{\theta JC}$ | 14.8 | $^\circ\text{C}/\text{W}$ |
| Operating and Storage Temperature Range | T_J, T_{STG} | -55 to +175 | $^\circ\text{C}$ | |

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|--|---------------------|-----|-------------|------------|------------------|--|
| OFF CHARACTERISTICS (Note 9) | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | 40 | — | — | V | $V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$ |
| Zero Gate Voltage Drain Current | I_{DSS} | — | — | 1 | μA | $V_{DS} = 32\text{V}, V_{GS} = 0\text{V}$ |
| Gate-Source Leakage | I_{GSS} | — | — | ± 100 | nA | $V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$ |
| ON CHARACTERISTICS (Note 9) | | | | | | |
| Gate Threshold Voltage | $V_{GS(\text{TH})}$ | 1 | 1.7 | 3 | V | $V_{DS} = V_{GS}, I_D = 250\mu\text{A}$ |
| Static Drain-Source On-Resistance | $R_{DS(\text{ON})}$ | — | 9.1 12.9 | 11.5 18 | $\text{m}\Omega$ | $V_{GS} = 10\text{V}, I_D = 10\text{A}$ $V_{GS} = 4.5\text{V}, I_D = 8.5\text{A}$ |
| Diode Forward Voltage | V_{SD} | — | 0.8 | 1.0 | V | $V_{GS} = 0\text{V}, I_S = 10\text{A}$ |
| DYNAMIC CHARACTERISTICS (Note 10) | | | | | | |
| Input Capacitance | C_{iss} | — | 1030 | — | pF | $V_{DS} = 20\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$ |
| Output Capacitance | C_{oss} | — | 324 | — | | |
| Reverse Transfer Capacitance | C_{rss} | — | 27 | — | | |
| Gate Resistance | R_g | — | 1.82 | — | Ω | $V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$ |
| Total Gate Charge ($V_{GS} = 4.5\text{V}$) | Q_g | — | 6.8 | — | nC | $V_{DD} = 20\text{V}, I_D = 10\text{A}$ |
| Total Gate Charge ($V_{GS} = 10\text{V}$) | Q_g | — | 14.2 | — | | |
| Gate-Source Charge | Q_{gs} | — | 2.0 | — | | |
| Gate-Drain Charge | Q_{gd} | — | 2.7 | — | ns | $V_{DD} = 20\text{V}, V_{GS} = 10\text{V}, R_g = 6\Omega, I_D = 10\text{A}$ |
| Turn-On Delay Time | $t_{D(\text{ON})}$ | — | 3.1 | — | | |
| Turn-On Rise Time | t_R | — | 3.1 | — | | |
| Turn-Off Delay Time | $t_{D(\text{OFF})}$ | — | 14.2 | — | ns | $I_F = 10\text{A}, dI/dt = 100\text{A}/\mu\text{s}$ |
| Turn-Off Fall Time | t_F | — | 5.8 | — | | |
| Reverse-Recovery Time | t_{RR} | — | 19.6 | — | | |
| Reverse-Recovery Charge | Q_{RR} | — | 8.2 | — | nC | |

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

7. Thermal resistance from junction to soldering point (on the exposed drain pad).

8. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^\circ\text{C}$.

9. Short duration pulse test used to minimize self-heating effect.

10. Guaranteed by design. Not subject to product testing.

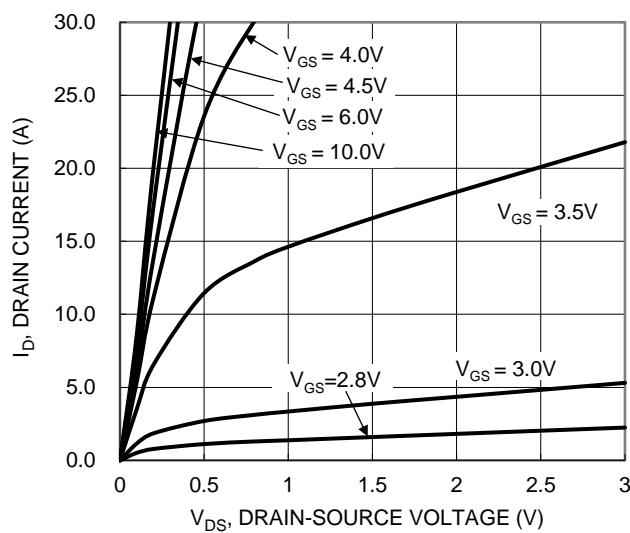


Figure 1. Typical Output Characteristic

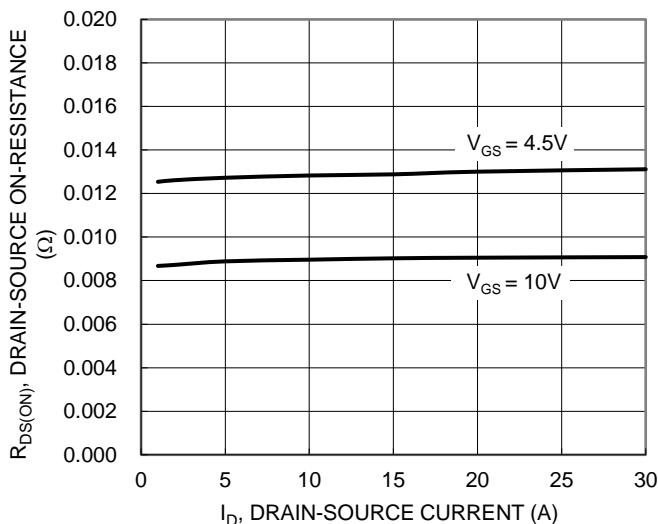


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

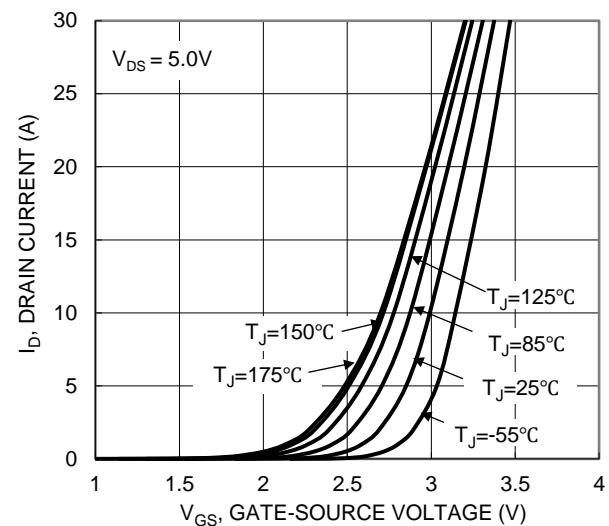


Figure 2. Typical Transfer Characteristic

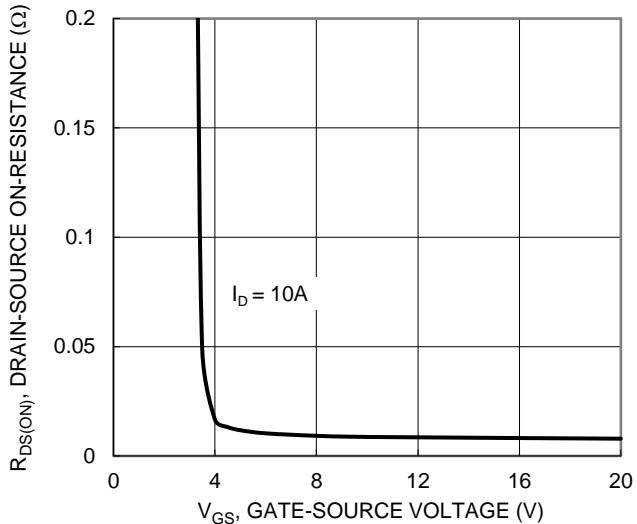


Figure 4. Typical Transfer Characteristic

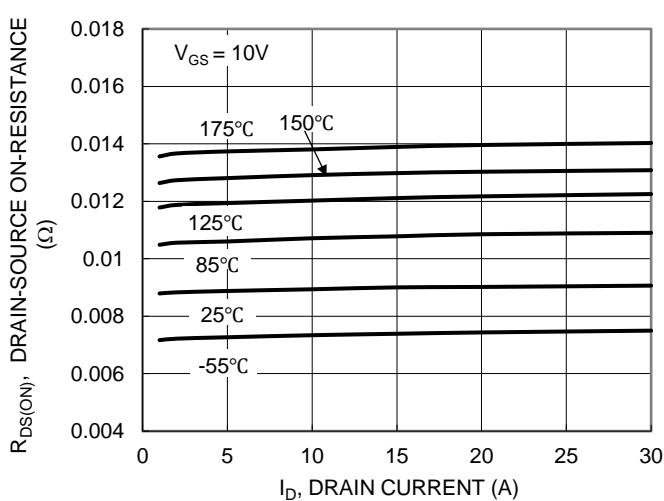


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

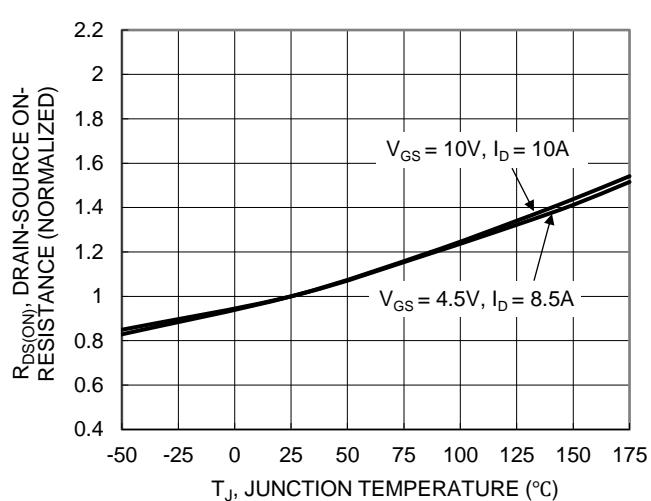
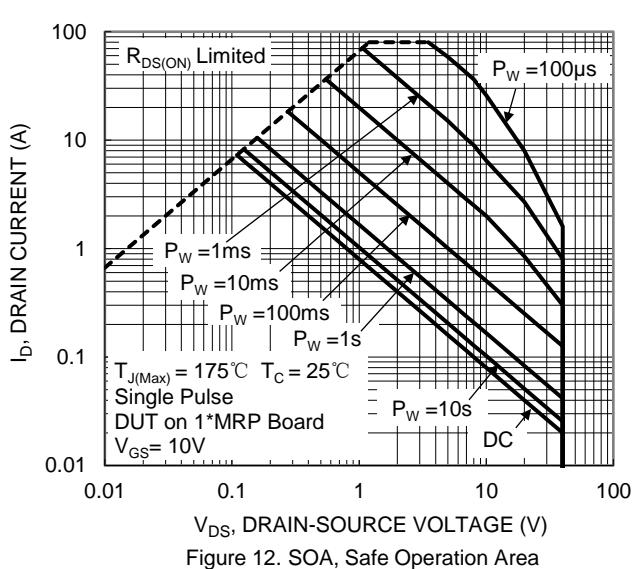
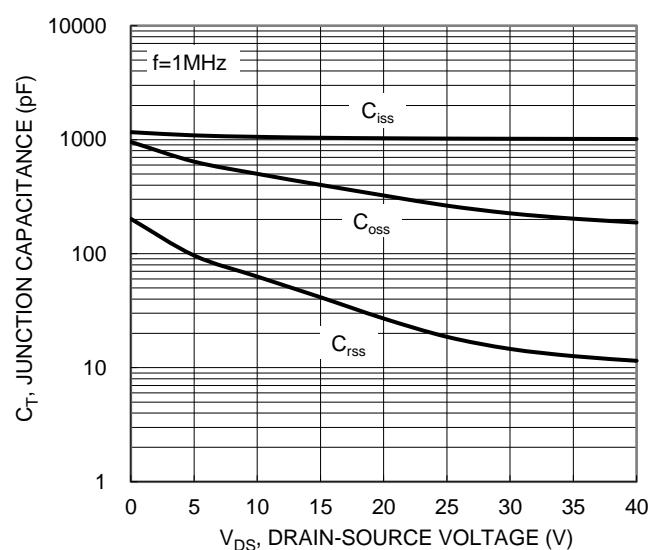
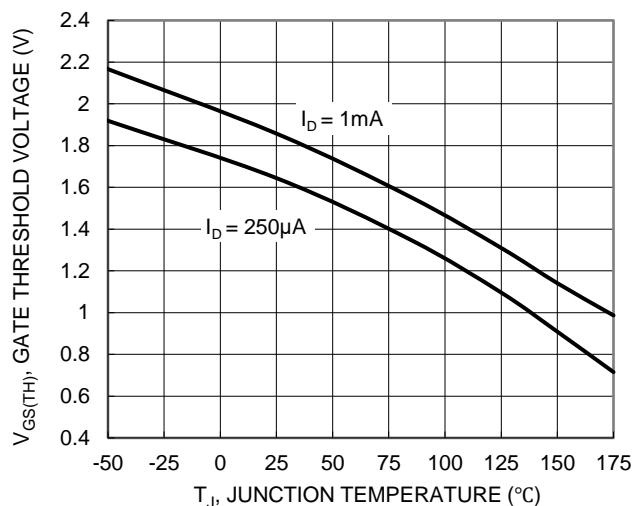
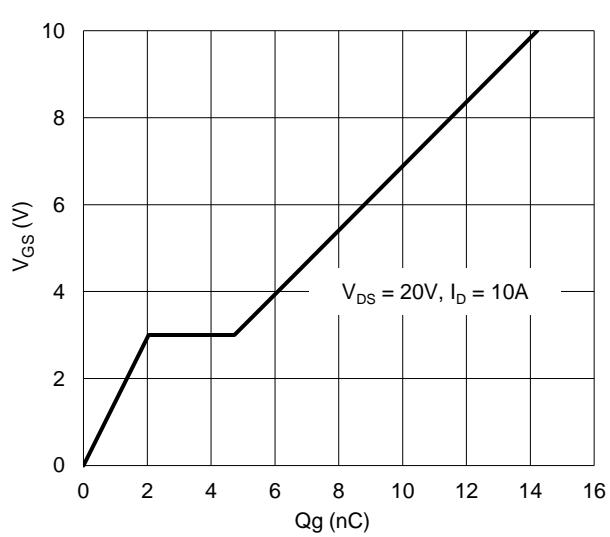
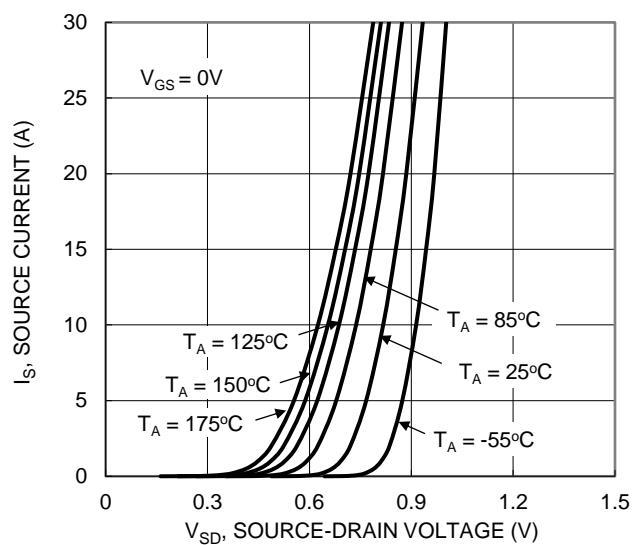
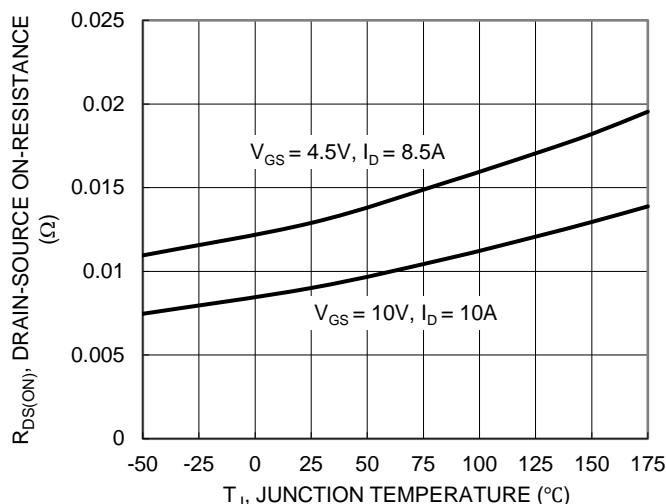


Figure 6. On-Resistance Variation with Temperature



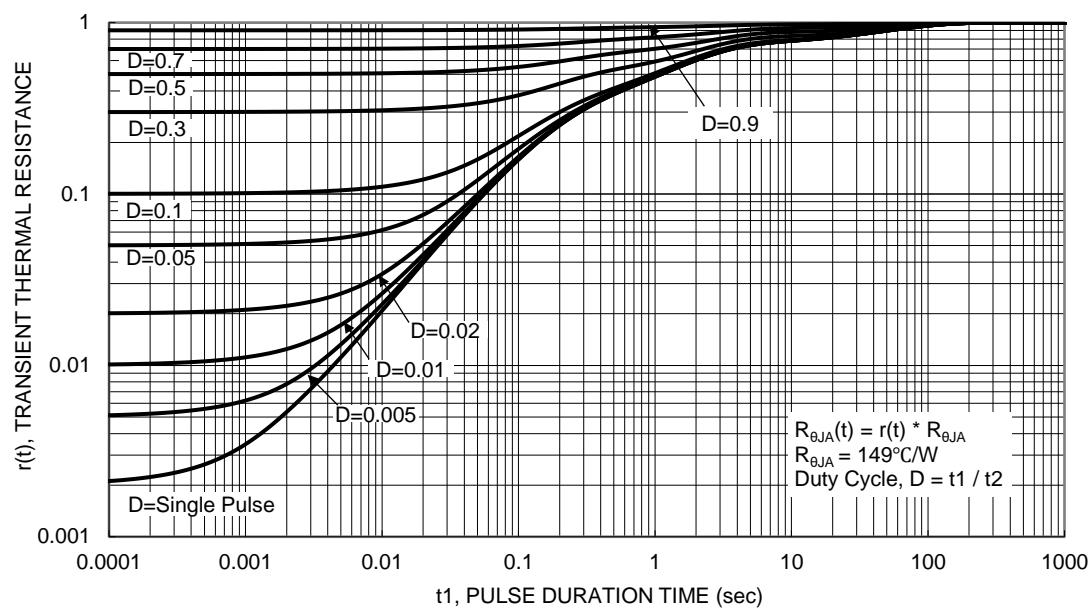
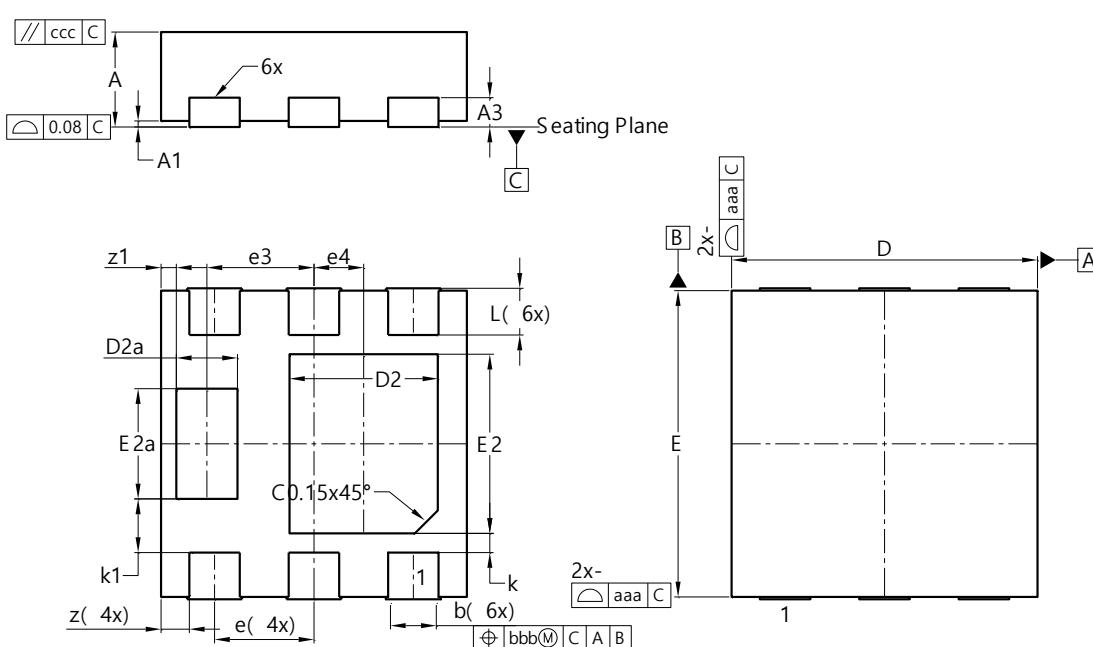


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

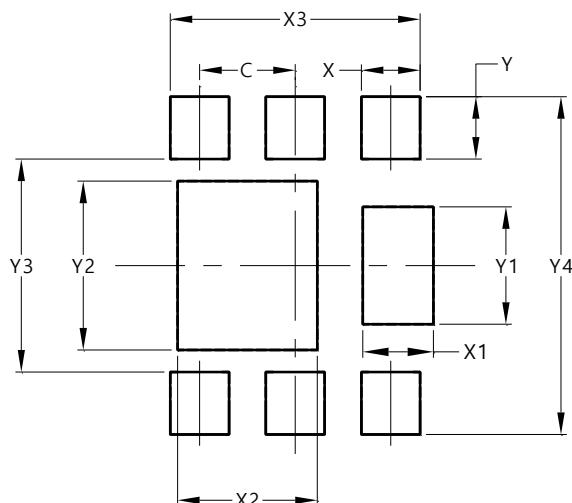
U-DFN2020-6/SWP (Type F)



Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2020-6/SWP (Type F)



| Dimensions | Value (in mm) |
|------------|---------------|
| C | 0.650 |
| X | 0.400 |
| X1 | 0.480 |
| X2 | 0.950 |
| X3 | 1.700 |
| Y | 0.425 |
| Y1 | 0.800 |
| Y2 | 1.150 |
| Y3 | 1.450 |
| Y4 | 2.300 |

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